

# MCU Function Analysis

## Table of Contents

1. Device Summary
2. Device Identification
  - 2.1. Package Marking
  - 2.2. Die Marking
  - 2.3. Device Images
    - 2.3.1. Top View
    - 2.3.2. Detail View
3. Process
  - 3.1 Cross-sectional view
  - 3.2 Minimum Pitch Metal
  - 3.3 Minimum Gate Length Transistor
4. Function Analysis
  - 4.1 Die-architecture & area
  - 4.2 Function blocks
    - 4.2.1 Function Blocks Measurements
5. Memory Information
  - 5.1 Memory Blocks Identification
  - 5.2 EEPROM
    - 5.2.1 EEPROM Region
    - 5.2.2 EEPROM Array
    - 5.2.3 EEPROM Unit
  - 5.3 FLASH
    - 5.3.1 FLASH Region
    - 5.3.2 FLASH Array
    - 5.3.3 FLASH Unit
  - 5.4 SRAM
    - 5.4.1 SRAM Region
    - 5.4.2 SRAM Array
    - 5.4.3 SRAM Unit
  - 5.5 Memory Parameter